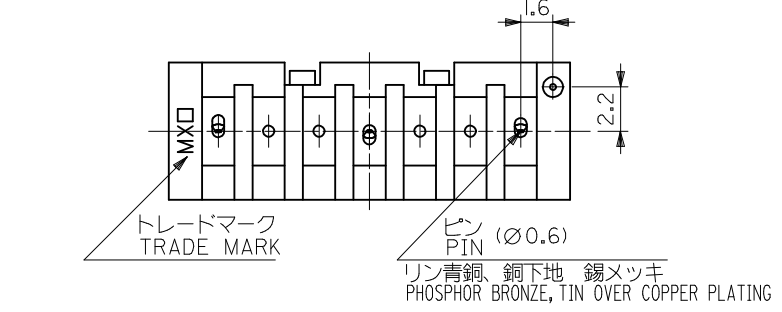
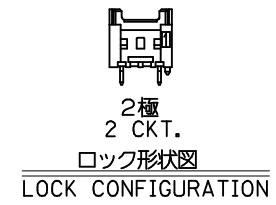
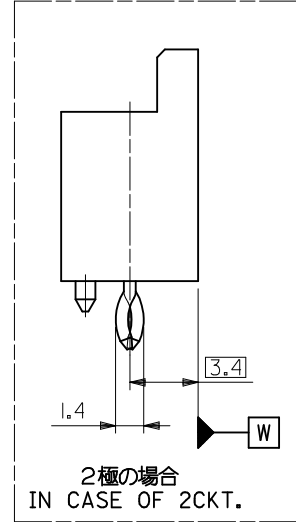
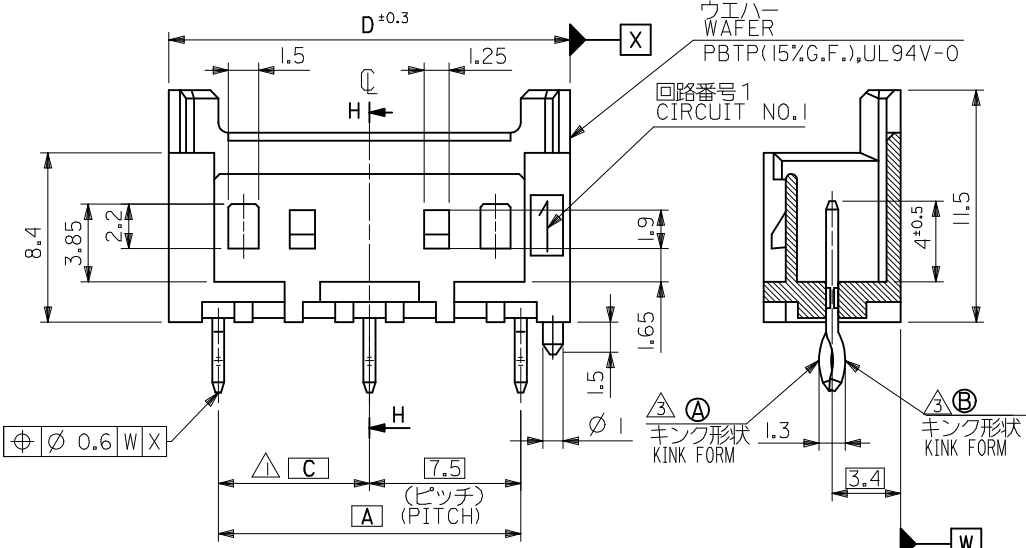


**注記 NOTES**

△ ウエハの  $\phi$  から隣接するピンの  $\phi$  までの位置を示す。  
SHOW POSITION FROM  $\phi$  OF WAFER TO  $\phi$  OF ADJACENT PIN.

2. 嵌合相手：51102,51103 シリーズ  
MATES WITH：51102,51103 SERIES.

△ 3極以上のキンク形状は両サイドが (A)、その他の極はすべて (B) 形状とする。  
KINK FORM MORE THAN 2 CURCUIT:  
PINS AT BOTH ENDS ARE KINK FORMED TO (A),  
THE OTHER PINS ARE KINK FORMED TO (B).



REVISED EC NO: J2017-0525 DRW:SSAT002 2017/04/13 CHK:DAIDA 2017/04/13 APPR:TKANEKO 2017/04/14	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 4.0	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	0.25 UNDER	UNDER	±	DRAWN BY K. TOJO	DATE 1992/12/22	TITLE 7.5 WIRE TO BOARD CONN. WAFER ASSY -LEAD FREE-	
	0.25 OVER	0.5 UNDER	±	CHECKED BY H. HIRAMOTO	DATE 1993/07/16	<b>molex</b> SD-53388-**10	
	0.5 OVER	1.0 UNDER	±	APPROVED BY	DATE		
1.0 OVER	10 UNDER	±0.2	MATERIAL NO.		DOCUMENT NO.	SHEET NO.	
10 OVER	30 UNDER	±0.25	SEE CHART		SD-53388-**10	1 OF 1	
30 OVER		±0.3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
ANGULAR ±3 °			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		